

**RADIATION HARDENED  
POWER MOSFET  
THRU-HOLE (Tabless - Low-Ohmic TO-254AA)**

**IRHMB57Z60  
30V, N-CHANNEL  
R5 TECHNOLOGY**

**Product Summary**

| Part Number | Radiation Level | RDS(on) | ID   |
|-------------|-----------------|---------|------|
| IRHMB57Z60  | 100K Rads (Si)  | 0.0055Ω | 45A* |
| IRHMB53Z60  | 300K Rads (Si)  | 0.0055Ω | 45A* |
| IRHMB54Z60  | 600K Rads (Si)  | 0.0055Ω | 45A* |
| IRHMB58Z60  | 1000K Rads (Si) | 0.0055Ω | 45A* |



International Rectifier's R5™ technology provides high performance power MOSFETs for space applications. These devices have been characterized for Single Event Effects (SEE) with useful performance up to an LET of 80 (MeV/(mg/cm²)). The combination of low RDS(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

**Features:**

- Low RDS(on)
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Ceramic Eyelets
- Electrically Isolated
- Light Weight
- ESD Rating: Class 3B per MIL-STD-750, Method 1020

**Absolute Maximum Ratings**

**Pre-Irradiation**

|                            | Parameter                       |                                           | Units |
|----------------------------|---------------------------------|-------------------------------------------|-------|
| ID @ VGS = 12V, TC = 25°C  | Continuous Drain Current        | 45*                                       | A     |
| ID @ VGS = 12V, TC = 100°C | Continuous Drain Current        | 45*                                       |       |
| IDM                        | Pulsed Drain Current ①          | 180                                       |       |
| PD @ TC = 25°C             | Max. Power Dissipation          | 208                                       | W     |
|                            | Linear Derating Factor          | 1.67                                      | W/°C  |
| VGS                        | Gate-to-Source Voltage          | ±20                                       | V     |
| EAS                        | Single Pulse Avalanche Energy ② | 1250                                      | mJ    |
| IAR                        | Avalanche Current ①             | 45                                        | A     |
| EAR                        | Repetitive Avalanche Energy ①   | 20.8                                      | mJ    |
| dv/dt                      | Peak Diode Recovery dv/dt ③     | 1.08                                      | V/ns  |
| TJ                         | Operating Junction              | -55 to 150                                | °C    |
| TSTG                       | Storage Temperature Range       |                                           |       |
|                            | Lead Temperature                | 300 (0.063 in. /1.6 mm from case for 10s) |       |
|                            | Weight                          | 8.0 (Typical)                             | g     |

\* Current is limited by package

For footnotes refer to the last page

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**Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)**

|                                     | Parameter                                    | Min | Typ  | Max    | Units | Test Conditions                                                                                                                                                  |
|-------------------------------------|----------------------------------------------|-----|------|--------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| B <sub>V</sub> DSS                  | Drain-to-Source Breakdown Voltage            | 30  | —    | —      | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.0mA                                                                                                                     |
| ΔB <sub>V</sub> DSS/ΔT <sub>J</sub> | Temperature Coefficient of Breakdown Voltage | —   | 0.03 | —      | V/°C  | Reference to 25°C, I <sub>D</sub> = 1.0mA                                                                                                                        |
| R <sub>DS(on)</sub>                 | Static Drain-to-Source On-State Resistance   | —   | —    | 0.0055 | Ω     | V <sub>GS</sub> = 12V, I <sub>D</sub> = 45A④                                                                                                                     |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                       | 2.0 | —    | 4.0    | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1.0mA                                                                                                       |
| g <sub>fs</sub>                     | Forward Transconductance                     | 73  | —    | —      | S     | V <sub>DS</sub> = 15V, I <sub>DS</sub> = 45A ④                                                                                                                   |
| I <sub>DSS</sub>                    | Zero Gate Voltage Drain Current              | —   | —    | 10     | μA    | V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V                                                                                                                      |
|                                     |                                              | —   | —    | 25     |       | V <sub>DS</sub> = 24V,<br>V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C                                                                                           |
| I <sub>GSS</sub>                    | Gate-to-Source Leakage Forward               | —   | —    | 100    | nA    | V <sub>GS</sub> = 20V                                                                                                                                            |
| I <sub>GSS</sub>                    | Gate-to-Source Leakage Reverse               | —   | —    | -100   |       | V <sub>GS</sub> = -20V                                                                                                                                           |
| Q <sub>g</sub>                      | Total Gate Charge                            | —   | —    | 240    | nC    | V <sub>GS</sub> = 12V, I <sub>D</sub> = 45A                                                                                                                      |
| Q <sub>gs</sub>                     | Gate-to-Source Charge                        | —   | —    | 60     |       | V <sub>DS</sub> = 15V                                                                                                                                            |
| Q <sub>gd</sub>                     | Gate-to-Drain ('Miller') Charge              | —   | —    | 55     |       |                                                                                                                                                                  |
| t <sub>d(on)</sub>                  | Turn-On Delay Time                           | —   | —    | 35     | ns    | V <sub>DD</sub> = 15V, I <sub>D</sub> = 45A                                                                                                                      |
| t <sub>r</sub>                      | Rise Time                                    | —   | —    | 175    |       | V <sub>GS</sub> = 12V, R <sub>G</sub> = 2.35Ω                                                                                                                    |
| t <sub>d(off)</sub>                 | Turn-Off Delay Time                          | —   | —    | 80     |       |                                                                                                                                                                  |
| t <sub>f</sub>                      | Fall Time                                    | —   | —    | 40     |       |                                                                                                                                                                  |
| L <sub>S</sub> + L <sub>D</sub>     | Total Inductance                             | —   | 6.8  | —      | nH    | Measured from Drain lead (6mm /0.25in. from package) to Source lead (6mm /0.25in. from package) with Source wires internally bonded from Source Pin to Drain Pad |
| C <sub>iss</sub>                    | Input Capacitance                            | —   | 8884 | —      | pF    | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V                                                                                                                      |
| C <sub>oss</sub>                    | Output Capacitance                           | —   | 4334 | —      |       | f = 1.0MHz                                                                                                                                                       |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                 | —   | 270  | —      |       |                                                                                                                                                                  |
| R <sub>g</sub>                      | Internal Gate Resistance                     | —   | 0.73 | —      | Ω     | f = 1.0MHz, open drain                                                                                                                                           |

**Source-Drain Diode Ratings and Characteristics**

|                 | Parameter                              | Min                                                                                                                  | Typ | Max | Units | Test Conditions                                                     |
|-----------------|----------------------------------------|----------------------------------------------------------------------------------------------------------------------|-----|-----|-------|---------------------------------------------------------------------|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —                                                                                                                    | —   | 45* | A     |                                                                     |
| I <sub>SM</sub> | Pulse Source Current (Body Diode)①     | —                                                                                                                    | —   | 180 |       |                                                                     |
| V <sub>SD</sub> | Diode Forward Voltage                  | —                                                                                                                    | —   | 1.2 | V     | T <sub>j</sub> = 25°C, I <sub>S</sub> = 45A, V <sub>GS</sub> = 0V ④ |
| t <sub>rr</sub> | Reverse Recovery Time                  | —                                                                                                                    | —   | 140 | ns    | T <sub>j</sub> = 25°C, I <sub>F</sub> = 45A, di/dt ≤ 100A/μs        |
| Q <sub>RR</sub> | Reverse Recovery Charge                | —                                                                                                                    | —   | 350 | μC    | V <sub>DD</sub> ≤ 25V ④                                             |
| t <sub>on</sub> | Forward Turn-On Time                   | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> . |     |     |       |                                                                     |

\* Current is limited by package

**Thermal Resistance**

|                   | Parameter           | Min | Typ  | Max  | Units | Test Conditions      |
|-------------------|---------------------|-----|------|------|-------|----------------------|
| R <sub>thJC</sub> | Junction-to-Case    | —   | —    | 0.60 | °C/W  |                      |
| R <sub>thCS</sub> | Case-to-Sink        | —   | 0.21 | —    |       |                      |
| R <sub>thJA</sub> | Junction-to-Ambient | —   | —    | 48   |       | Typical socket mount |

**Note:** Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

## Radiation Characteristics

## IRHMB57Z60

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

**Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥**

|                     | Parameter                                                                     | Up to 600K Rads(Si) <sup>1</sup> |        | 1000K Rads (Si) <sup>2</sup> |        | Units | Test Conditions                                            |
|---------------------|-------------------------------------------------------------------------------|----------------------------------|--------|------------------------------|--------|-------|------------------------------------------------------------|
|                     |                                                                               | Min                              | Max    | Min                          | Max    |       |                                                            |
| BV <sub>DSS</sub>   | Drain-to-Source Breakdown Voltage                                             | 30                               | —      | 30                           | —      | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.0mA               |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                                                        | 2.0                              | 4.0    | 1.5                          | 4.0    |       | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 1.0mA |
| I <sub>GSS</sub>    | Gate-to-Source Leakage Forward                                                | —                                | 100    | —                            | 100    | nA    | V <sub>GS</sub> = 20V                                      |
| I <sub>GSS</sub>    | Gate-to-Source Leakage Reverse                                                | —                                | -100   | —                            | -100   |       | V <sub>GS</sub> = -20 V                                    |
| I <sub>DSS</sub>    | Zero Gate Voltage Drain Current                                               | —                                | 10     | —                            | 25     | μA    | V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V                |
| R <sub>DS(on)</sub> | Static Drain-to-Source <sup>④</sup><br>On-State Resistance (TO-3)             | —                                | 0.0040 | —                            | 0.0045 | Ω     | V <sub>GS</sub> = 12V, I <sub>D</sub> = 45A                |
| R <sub>DS(on)</sub> | Static Drain-to-Source On-State <sup>④</sup><br>Resistance (Low-Ohmic TO-254) | —                                | 0.0055 | —                            | 0.0060 | Ω     | V <sub>GS</sub> = 12V, I <sub>D</sub> = 45A                |
| V <sub>SD</sub>     | Diode Forward Voltage <sup>④</sup>                                            | —                                | 1.2    | —                            | 1.2    | V     | V <sub>GS</sub> = 0V, I <sub>S</sub> = 45A                 |

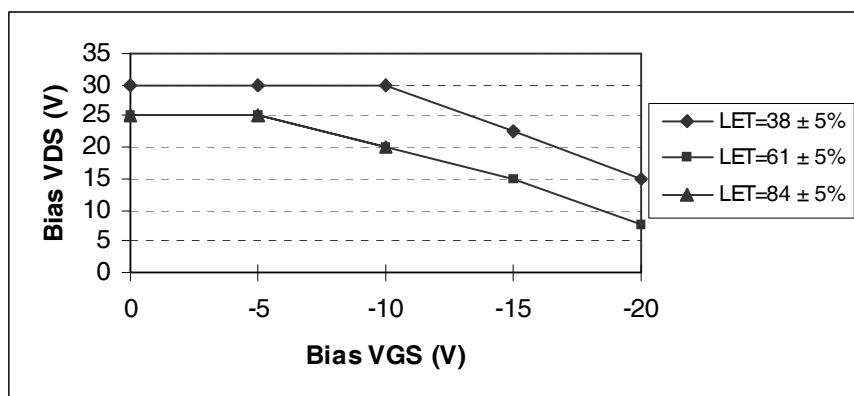
1. Part numbers IRHMB57Z60, IRHMB53Z60 and IRHMB54Z60

2. Part number IRHMB58Z60

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

**Table 2. Typical Single Event Effect Safe Operating Area**

| LET<br>(MeV/(mg/cm <sup>2</sup> )) | Energy<br>(MeV) | Range<br>(μm) | VDS (V)      |               |                |                |                |
|------------------------------------|-----------------|---------------|--------------|---------------|----------------|----------------|----------------|
|                                    |                 |               | @VGS =<br>0V | @VGS =<br>-5V | @VGS =<br>-10V | @VGS =<br>-15V | @VGS =<br>-20V |
| 38 ± 5%                            | 300 ± 7.5%      | 38 ± 7.5%     | 30           | 30            | 30             | 22.5           | 15             |
| 61 ± 5%                            | 330 ± 7.5%      | 31 ± 10%      | 25           | 25            | 20             | 15             | 7.5            |
| 84 ± 5%                            | 350 ± 10%       | 28 ± 7.5%     | 25           | 25            | 20             | -              | -              |



**Fig a. Typical Single Event Effect, Safe Operating Area**

For footnotes refer to the last page

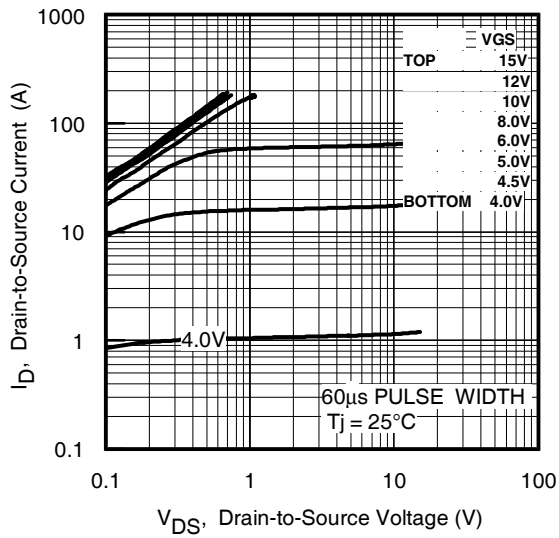


Fig 1. Typical Output Characteristics

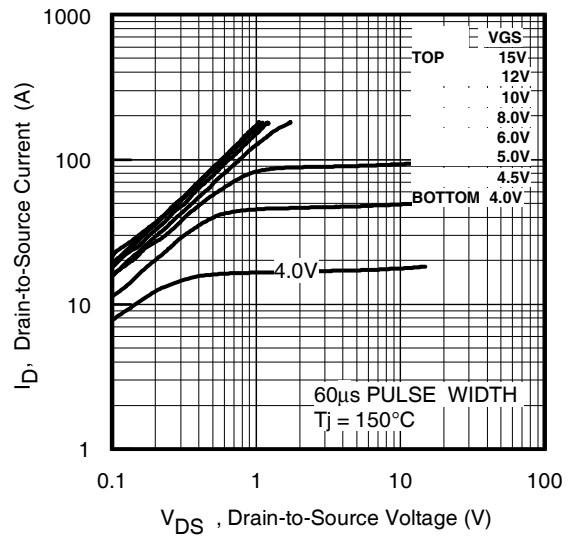


Fig 2. Typical Output Characteristics

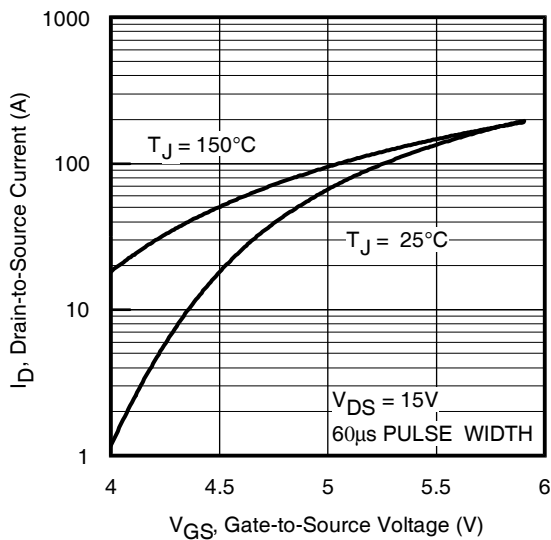
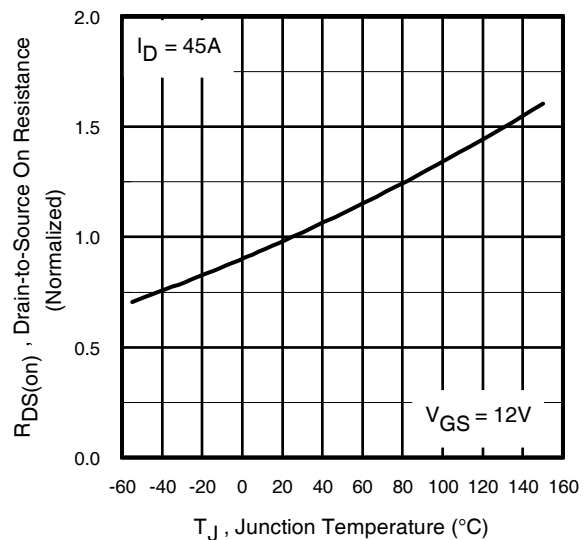
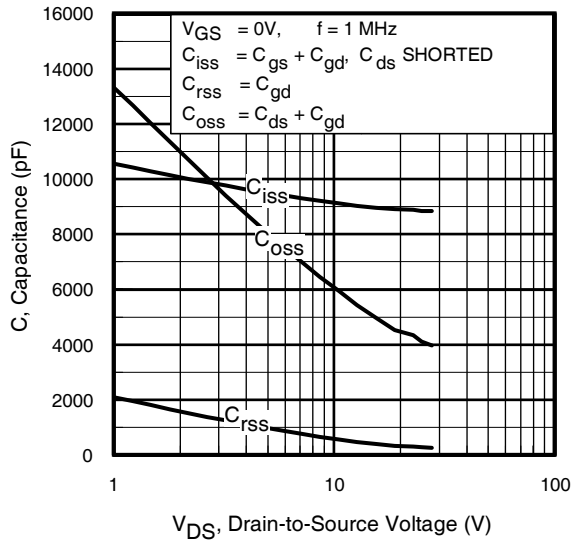
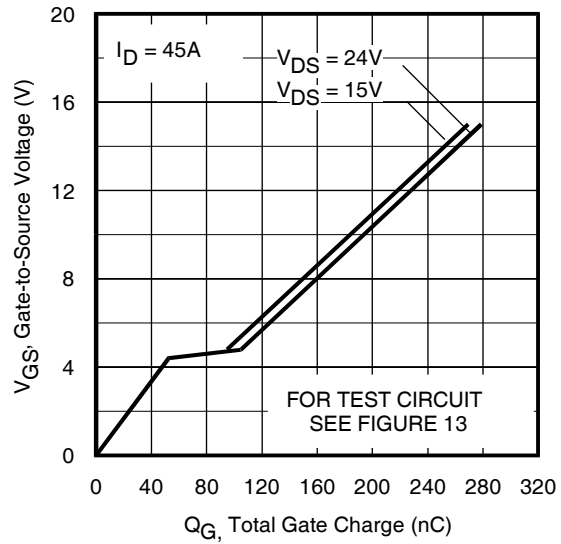


Fig 3. Typical Transfer Characteristics

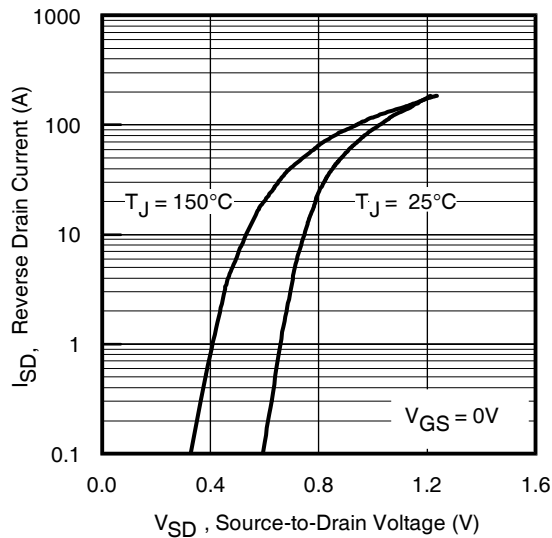
Fig 4. Normalized On-Resistance  
Vs. Temperature



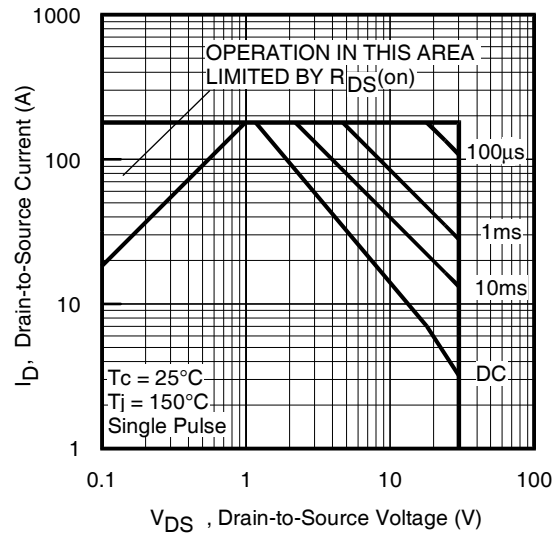
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



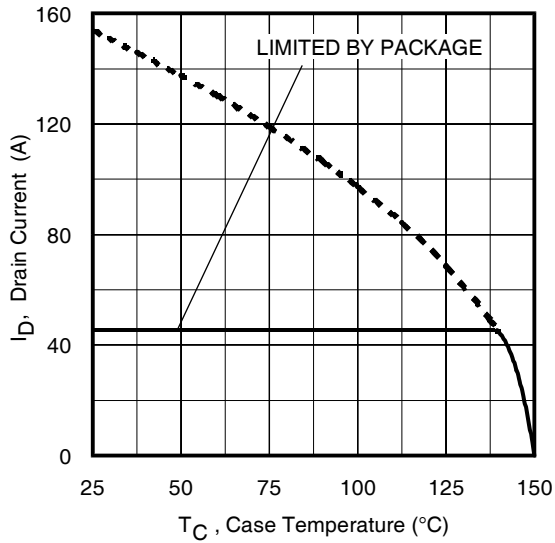
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



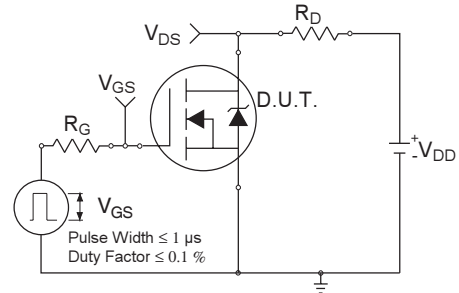
**Fig 7.** Typical Source-Drain Diode Forward Voltage



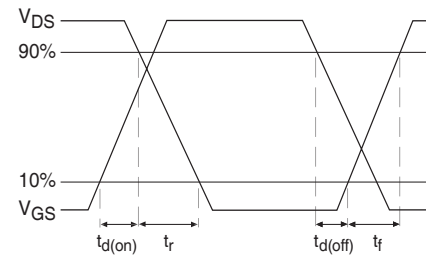
**Fig 8.** Maximum Safe Operating Area



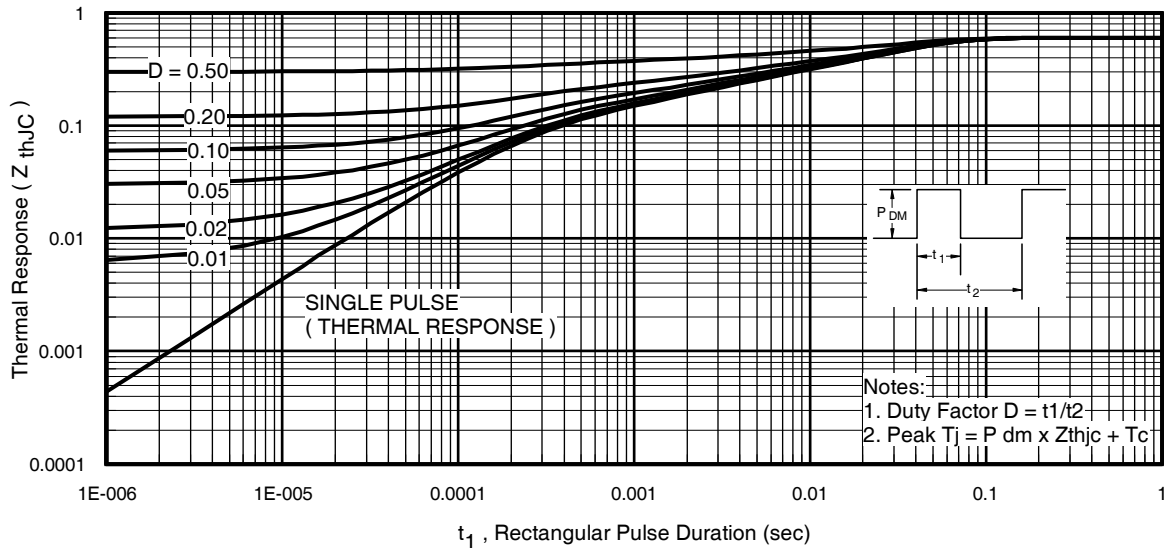
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



**Fig 10b.** Switching Time Waveforms



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

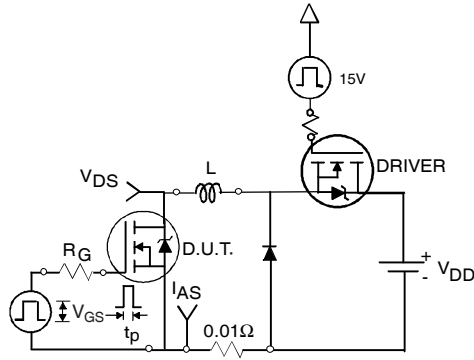


Fig 12a. Unclamped Inductive Test Circuit

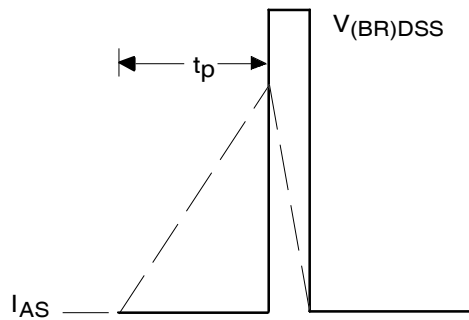


Fig 12b. Unclamped Inductive Waveforms

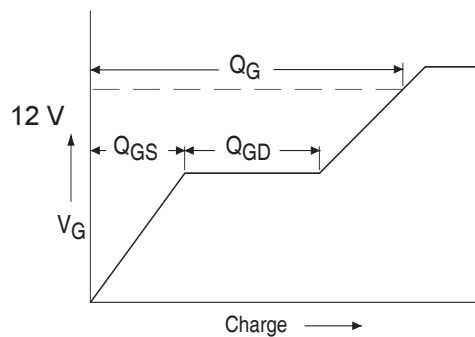


Fig 13a. Basic Gate Charge Waveform

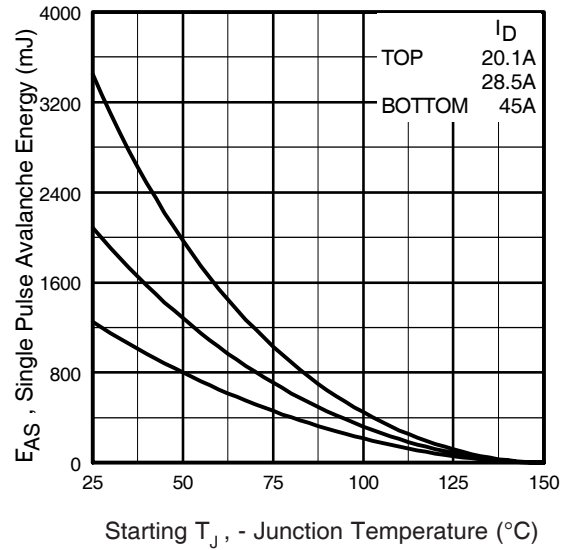


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

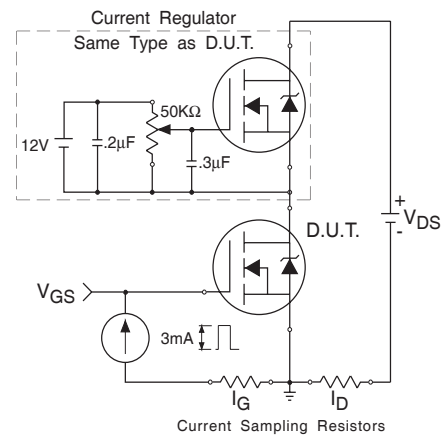


Fig 13b. Gate Charge Test Circuit

## IRHMB57Z60

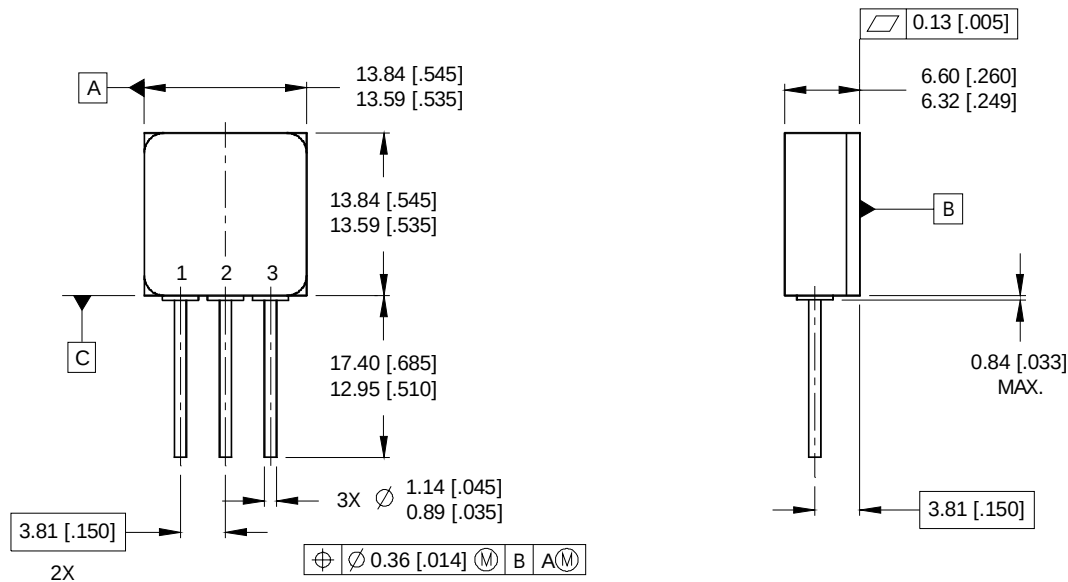
## Pre-Irradiation

### Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = 25V$ , starting  $T_J = 25^\circ C$ ,  $L = 1.1\text{ mH}$   
Peak  $I_L = 45A$ ,  $V_{GS} = 12V$
- ③  $I_{SD} \leq 45A$ ,  $di/dt \leq 150A/\mu s$ ,  
 $V_{DD} \leq 30V$ ,  $T_J \leq 150^\circ C$

- ④ Pulse width  $\leq 300\text{ }\mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤ **Total Dose Irradiation with  $V_{GS}$  Bias.**  
12 volt  $V_{GS}$  applied and  $V_{DS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with  $V_{DS}$  Bias.**  
24 volt  $V_{DS}$  applied and  $V_{GS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.

### Case Outline and Dimensions — Tabless - Low-Ohmic TO-254AA



#### NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-254AA.

#### CAUTION

#### BERYLLIA WARNING PER MIL-PRF-19500

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

International  
**IR** Rectifier

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